

REMARKS

Specification

The Examiner stated that the spacing of the lines of the specification is such as to make reading and entry of amendments difficult. The Examiner further required new application papers with lines double spaced on good quality paper.

Applicant has submitted a substitute specification, excluding claims, with lines double spaced on good quality paper. No new matter has been added, and a marked-up version has not been included because no amendments were made, as only the spacing of the text was changed.

35 U.S.C. § 102 Rejections

The Examiner has rejected claims 1-24 under 35 U.S.C. § 102(b) as being anticipated by Whiting.

Claims 1, 9, 15 and 20 have been amended to include measuring metrological attributes to control the temperature of a substrate. Specifically, claims 1, 15, and 20 include the limitation “a measurement processing module to measure metrological attributes of said substrate and generate substrate metrological attribute information.” Claim 9 includes the limitation “measuring metrological attributes of said substrates” and “generating substrate metrological attribute information based on said measured attributes.”

Whiting does not disclose measuring metrological attributes to control the temperature of a substrate. Whiting discloses a method for the control of wafer surface temperatures during a post exposure bake on hot plates of wafers which carry integrated circuits (Abstract). As illustrated in Fig. 1, a hot plate 10 is connected to a controller 12 for adjusting the temperature of at least the upper surface 14 of the hot plate 10 (col. 3, lines 63-65). The hot plate 10 may be divided into a plurality of zones 16 on surface 14, each having heating filaments or elements 18 embedded therein. In response to the temperature controller 12, the heating elements 18 may provide for either a uniformly heated hot plate surface 14 or an adjustment of the individual zones 16 of the surface 14 in accordance with specific conditions (col. 3, line 66-col. 4, line 5). Positioned at a space relationship above the wafer is an array 22 of thermal detectors 24 which are acted upon by either an infrared camera 26 or a pyroelectric or pyrothermal component 28 for detecting the surface temperature of the wafer 10 in correlation with a particular location relative to the thermal detection array 22 located thereabove (col. 4, lines 17-22).

The infrared camera 26 or pyroelectric or pyrothermal component 28 is adapted to map the obtained temperature data from the upper surface 14 of the wafer 20 into the hot plate zones 16 relative to the position of the wafer 20. Then this data is used for adjusting and controlling the temperature of the hot plate surface 14 and more particularly the individual hot plate zones 16 through the controller 12 (col. 4, lines 23-32). No other detection mechanisms, beside temperature detection mechanisms, are disclosed in Whiting. Whiting thus

discloses an array of temperature sensors used for adjusting the temperature of a hot plate. Specifically, Whiting does not disclose measuring metrological attributes to control the temperature of a substrate.

Therefore, claims 1, 9, 15, and 20 are not anticipated by Whiting because it does not disclose measuring metrological attributes to control the temperature of a substrate.

Therefore, claims 1, 9, 15, and 20 are not anticipated by Whiting because claims 1, 9, 15, and 20 include a limitation that is not disclosed in Whiting.

Claims 2-9, 10-12, 16-19, and 21-24 are dependent on either claim 1, claim 9, claim 15, or claim 20 and should be allowable for the same reasons as claims 1, 9, 15, and 20 stated above.

Claims 13 and 14 have been cancelled.

Applicant, accordingly, respectfully requests withdrawal of the rejections of claims 1-12 and 15-24 under 35 U.S.C. § 102(b) as being anticipated by Whiting.

Applicant respectfully submits that the present application is in condition for allowance. If the Examiner believes a telephone conference would expedite or assist in the allowance of the present application, the Examiner is invited to call Mark A. Kupanoff at (408) 720-8300.

Pursuant to 37 C.F.R. 1.136(a)(3), Applicant hereby requests and authorizes the U.S. Patent and Trademark Office to (1) treat any concurrent or future reply that requires a petition for extension of time as incorporating a petition for extension of time for the appropriate length of time and (2) charge all required fees, including extension of time fees and fees under 37 C.F.R. 1.16 and 1.17, to Deposit Account No. 02-2666.

Respectfully submitted,

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